

ABSTRACT

IC CARD

5 According to one embodiment, an IC card includes a
card base member, a film-shaped substrate, a structure, and
a stress concentration portion. The substrate is arranged
within the card base member and includes wiring. The
structure is mounted on the substrate, is connected to the
10 wiring, and is provided within the card base member. The
stress concentration portion is provided within the card
base member and in or outside the periphery of the
structure in a principal surface direction of the card base
member, the stress concentration portion on which stress
15 that is generated when an external force is applied is
concentrated.

FIG. 1